

**AMENDMENTS TO THE CLAIMS**

Claim 1 (Cancelled)

2. (Previously Presented) The method according to claim 14, wherein the first and second portions of the silicon layer initially have the same thickness.

3. (Previously Presented) The method according to claim 14, wherein the step of partially removing the first portion of the silicon layer includes etching the first portion.

4. (Original) The method according to claim 3, wherein the step of partially removing the first portion of the silicon layer includes depositing a resist over the silicon layer and exposing and developing the resist to expose the first portion of the silicon layer.

5. (Original) The method according to claim 3, wherein the thickness of the first portion is determined by etching the first portion for a predetermined length of time.

6. (Previously Presented) The method according to claim 14, wherein the step of partially removing the first portion of the silicon layer includes oxidizing the first portion of the silicon layer and removing the oxidized silicon.

**Application No.: 10/023,350**

layer and exposing and developing the resist to expose a portion of the mask layer over the first portion of the silicon layer and removing the mask layer over the first portion of the silicon layer.

8. (Original) The method according to claim 7, further comprising the step of removing the mask layer.

9. (Original) The method according to claim 7, wherein the mask layer is an antireflective material.

10. (Previously Presented) The method according to claim 7, wherein the mask layer is silicon nitride.

11. (Previously Presented) The method according to claim 14, wherein isolating features are formed before the first portion of the silicon layer is partially removed.

12. (Previously Presented) The method according to claim 14, wherein isolating features are formed after the first portion of the silicon layer is partially removed.

13. (Cancelled)

14. (Previously Presented) A method of manufacturing a semiconductor device,

providing a silicon layer over an insulating layer, the silicon layer including a first portion and a second portion;

partially removing the first portion of the silicon layer, wherein a thickness of the second portion is greater than a thickness of the first portion; and

forming a first transistor in the first portion and a second transistor in the second portion, wherein

the first transistor includes first source/drain regions and the second transistor includes second source/drain regions, and a depth of the second source/drain regions greater than a depth of the first source/drain regions.

15. (Previously Presented) The method according to claim 14, wherein the first source/drain regions are formed with a first dopant and the second source/drain regions are formed with a second dopant, and the diffusivity of the second dopant into silicon is greater than the diffusivity of the first dopant into silicon.

16. (Previously Presented) A semiconductor device, comprising:  
an insulating layer;  
a silicon layer over the insulating layer, the silicon layer including a first portion and a second portion; and  
a first transistor is formed in the first portion and a second transistor is formed in the second portion.

wherein the first transistor of the device includes first source/drain regions, and the second transistor of the device

**Application No.: 10/023,350**

second source/drain regions, and a depth of the second source/drain regions greater than a depth of the first source/drain regions.

Claim 17 (Cancelled)

18. (Previously Presented) The semiconductor device according to claim 16, wherein the first transistor includes source/drain regions formed with a first dopant and the second source/drain regions formed with a second dopant, and the diffusivity of the second dopant into silicon is greater than the diffusivity of the first dopant into silicon.

Claims 19-20 (Cancelled)